## Student Loan Repayment Program

Announcement for Fiscal Year 2018

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The Office of the Chief Human Capital Officer (OCHCO) is pleased to announce that plans are underway to administer the Student Loan Repayment Program (SLRP) for Fiscal Year 2018. The SLRP serves as a retention incentive for HUD employees who are considering leaving the Department to work outside the Federal government. The SLRP is designed to retain highly, or uniquely qualified employees in mission critical positions and/or positions that would otherwise be difficult to fill. For purposes of this program, mission critical positions are considered vital to the day-to-day operations, success of the Program Office and overall success of the Department. Eligible employees may receive up to \$6,000 per calendar year, not to exceed a maximum Departmental career benefit of \$40,000.

While we do not have an actual open and close date at this time, we wanted to alert our employees to check HUD@Work frequently. Due to the end of the fiscal year approaching soon, be advised the administration of this program will be executed at an accelerated pace.

The application window dates will be announced in a forthcoming staff bulletin. If you are planning to be on vacation in the next few weeks, we advise you to designate someone who can apply on your behalf.

Please stay tuned for a follow-up announcement which will provide additional information and resources for applying. If you have any questions about this staff bulletin, please contact Jovanni Robinson at 202-402-4572 or <u>jovanni.m.robinson@hud.gov</u>; or Kimberly Byrd at 202-402-5559 or <u>kimberly.m.byrd@hud.gov</u>